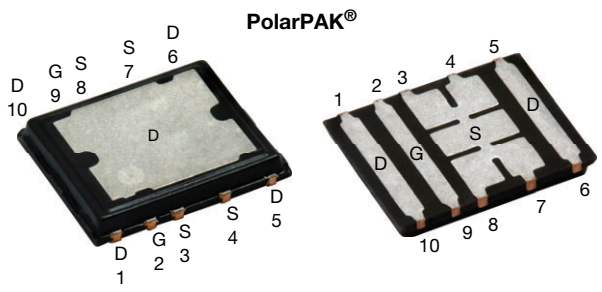
# N-Channel 75 V (D-S) MOSFET




Top View Bottom View

Top surface is connected to pins 1, 5, 6, and 10

## FEATURES

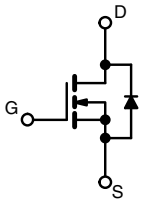
- TrenchFET® power MOSFET
- Ultra low thermal resistance using top-exposed PolarPAK® package for double-sided cooling
- Leadframe-based encapsulated package
  - Die not exposed
  - Same layout regardless of die size
- Low $Q_{gd}/Q_{gs}$ ratio helps prevent shoot-through
- 100 % $R_g$ and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT

HALOGEN FREE Available

## APPLICATIONS

- Primary side switch
- Half-bridge
- Synchronous rectification




N-Channel MOSFET

| PRODUCT SUMMARY | |
|---|---|
| $V_{DS}$ (V) | 75 |
| $R_{DS(on)}$ max. (Ω) at $V_{GS}$ = 10 V | 0.0095 |
| $R_{DS(on)}$ max. (Ω) at $V_{GS}$ = 4.5 V | 0.0125 |
| $Q_g$ typ. (nC) | 33 |
| $I_D$ (A) [a] (package limit) | 60 |
| $I_D$ (A) [a] (silicon limit) | 79 |
| Configuration | Single |

| ORDERING INFORMATION | |
|---|---|
| Package | PolarPAK |
| Lead (Pb)-free | SiE818DF-T1-E3 |
| Lead (Pb)-free and halogen-free | SiE818DF-T1-GE3 |

**ABSOLUTE MAXIMUM RATINGS** ($T_A$ = 25 °C, unless otherwise noted)

| PARAMETER | | SYMBOL | LIMIT | UNIT |
|---|---|---|---|---|
| Drain-source voltage | | $V_{DS}$ | 75 | V |
| Gate-source voltage | | $V_{GS}$ | ± 20 | |
| Continuous drain current ($T_J$ = 150 °C) | $T_C$ = 25 °C | $I_D$ | 60 [a] (package Limit) | A |
| | $T_C$ = 25 °C | | 79 (silicon Limit) | |
| | $T_C$ = 70 °C | | 60 [a] | |
| | $T_A$ = 25 °C | | 16 [b, c] | |
| | $T_A$ = 70 °C | | 12.9 [b, c] | |
| Pulsed drain current | | $I_{DM}$ | 80 | |
| Continuous source-drain diode current | $T_C$ = 25 °C | $I_S$ | 60 [a] | |
| | $T_A$ = 25 °C | | 4.3 [b, c] | |
| Single pulse avalanche current | L = 0.1 mH | $I_{AS}$ | 50 | |
| Avalanche energy | | $E_{AS}$ | 125 | mJ |
| Maximum power dissipation | $T_C$ = 25 °C | $P_D$ | 125 | W |
| | $T_C$ = 70 °C | | 80 | |
| | $T_A$ = 25 °C | | 5.2 [b, c] | |
| | $T_A$ = 70 °C | | 3.3 [b, c] | |
| Operating junction and storage temperature range | | $T_J$, $T_{stg}$ | -55 to +150 | °C |
| Soldering recommendations (peak temperature) [d, e] | | | 260 | |

**Notes**

a. Package limited
b. Surface mounted on 1" x 1" FR4 board
c. t = 10 s
d. See solder profile (www.vishay.com/doc?73257). The PolarPAK is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

## THERMAL RESISTANCE RATINGS

| PARAMETER | | SYMBOL | TYPICAL | MAXIMUM | UNIT |
|---|---|---|---|---|---|
| Maximum junction-to-ambient [a, b] | t ≤ 10 s | $R_{thJA}$ | 20 | 24 | °C/W |
| Maximum junction-to-case (drain top) | Steady state | $R_{thJC}$ (drain) | 0.8 | 1 | |
| Maximum junction-to-case (source) [a, c] | | $R_{thJC}$ (source) | 2.2 | 2.7 | |

**Notes**
a. Surface mounted on 1" x 1" FR4 board
b. Maximum under steady state conditions is 68 °C/W
c. Measured at source pin (on the side of the package)

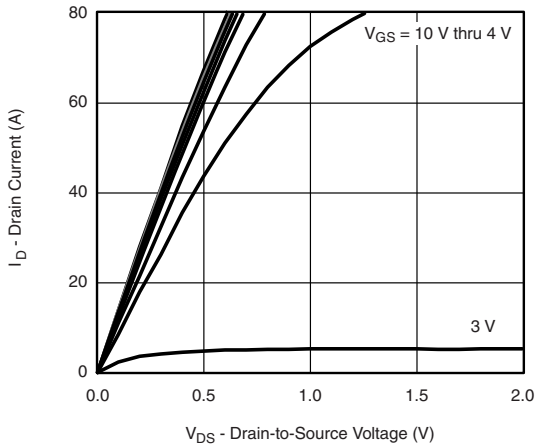
## SPECIFICATIONS ($T_J$ = 25 °C, unless otherwise noted)

| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|---|---|---|---|---|---|
| **Static** | | | | | | |
| Drain-source breakdown voltage | $V_{DS}$ | $V_{GS}$ = 0 V, $I_D$ = 250 µA | 75 | - | - | V |
| $V_{DS}$ temperature coefficient | $\Delta V_{DS}/T_J$ | $I_D$ = 250 µA | - | 78 | - | mV/°C |
| $V_{GS(th)}$ temperature coefficient | $\Delta V_{GS(th)}/T_J$ | | - | -7.1 | - | |
| Gate-source threshold voltage | $V_{GS(th)}$ | $V_{DS}$ = $V_{GS}$ , $I_D$ = 250 µA | 1.5 | 2.1 | 3 | V |
| Gate-source leakage | $I_{GSS}$ | $V_{DS}$ = 0 V, $V_{GS}$ = ± 20 V | - | - | ± 100 | nA |
| Zero gate voltage drain current | $I_{DSS}$ | $V_{DS}$ = 75 V, $V_{GS}$ = 0 V | - | - | 1 | µA |
| | | $V_{DS}$ = 75 V, $V_{GS}$ = 0 V, $T_J$ = 55 °C | - | - | 10 | |
| On-state drain current [a] | $I_{D(on)}$ | $V_{DS}$ ≥ 5 V, $V_{GS}$ = 10 V | 25 | - | - | A |
| Drain-source on-state resistance [a] | $R_{DS(on)}$ | $V_{GS}$ = 10 V, $I_D$ = 16 A | - | 0.0078 | 0.0095 | Ω |
| | | $V_{GS}$ = 4.5 V, $I_D$ = 14 A | - | 0.0103 | 0.0125 | |
| Forward transconductance [a] | $g_{fs}$ | $V_{DS}$ = 20 V, $I_D$ = 16 A | - | 50 | - | S |
| **Dynamic [b]** | | | | | | |
| Input capacitance | $C_{iss}$ | $V_{DS}$ = 38 V, $V_{GS}$ = 0 V, f = 1 MHz | - | 3200 | - | pF |
| Output capacitance | $C_{oss}$ | | - | 330 | - | |
| Reverse transfer capacitance | $C_{rss}$ | | - | 170 | - | |
| Total gate charge | $Q_g$ | $V_{DS}$ = 38 V, $V_{GS}$ = 10 V, $I_D$ = 16 A | - | 63 | 95 | nC |
| | | $V_{DS}$ = 38 V, $V_{GS}$ = 4.5 V, $I_D$ = 16 A | - | 33 | 50 | |
| Gate-source charge | $Q_{gs}$ | | - | 11 | - | |
| Gate-drain charge | $Q_{gd}$ | | - | 17 | - | |
| Gate resistance | $R_g$ | f = 1 MHz | - | 0.95 | 1.5 | Ω |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}$ = 38 V, $R_L$ = 3.8 Ω, $I_D$ ≅ 10 A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 Ω | - | 30 | 45 | ns |
| Rise time | $t_r$ | | - | 150 | 225 | |
| Turn-off delay time | $t_{d(off)}$ | | - | 40 | 60 | |
| Fall time | $t_f$ | | - | 15 | 25 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}$ = 38 V, $R_L$ = 3.8 Ω, $I_D$ ≅ 10 A, $V_{GEN}$ = 10 V, $R_g$ = 1 Ω | - | 15 | 25 | |
| Rise time | $t_r$ | | - | 15 | 25 | |
| Turn-off delay time | $t_{d(off)}$ | | - | 40 | 60 | |
| Fall time | $t_f$ | | - | 10 | 15 | |
| **Drain-Source Body Diode Characteristics** | | | | | | |
| Continuous source-drain diode current | $I_S$ | $T_C$ = 25 °C | - | - | 60 | A |
| Pulse diode forward current [a] | $I_{SM}$ | | - | - | 80 | |
| Body diode voltage | $V_{SD}$ | $I_S$ = 10 A | - | 0.8 | 1.2 | V |
| Body diode reverse recovery time | $t_{rr}$ | $I_F$ = 10 A, di/dt = 100 A/µs, $T_J$ = 25 °C | - | 100 | 150 | ns |
| Body diode reverse recovery charge | $Q_{rr}$ | | - | 345 | 520 | nC |
| Reverse recovery fall time | $t_a$ | | - | 75 | - | ns |
| Reverse recovery rise time | $t_b$ | | - | 25 | - | |

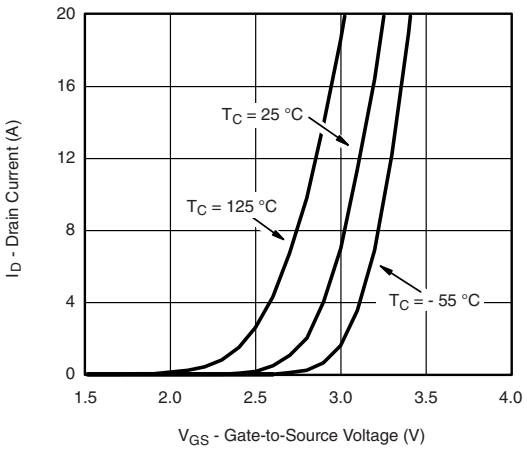
**Notes**
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %
b. Guaranteed by design, not subject to production testing

*Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

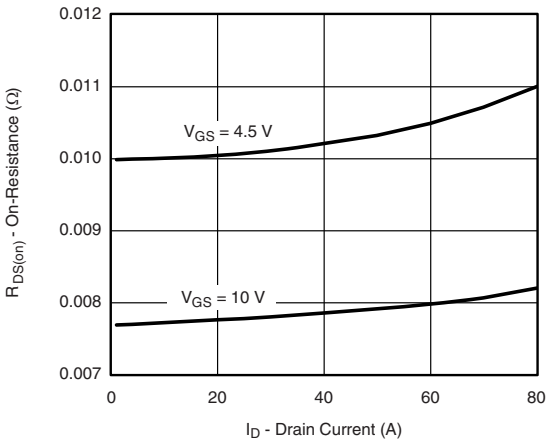
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



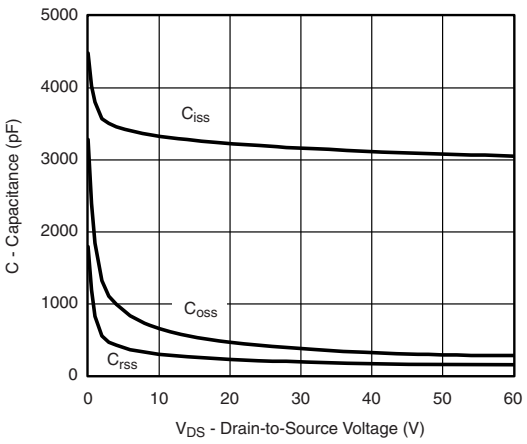

**Output Characteristics**



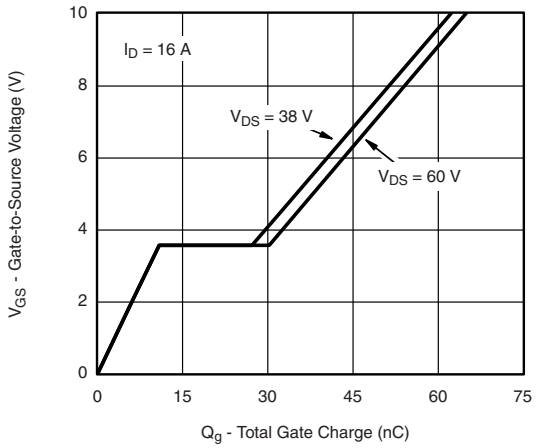

**Transfer Characteristics**



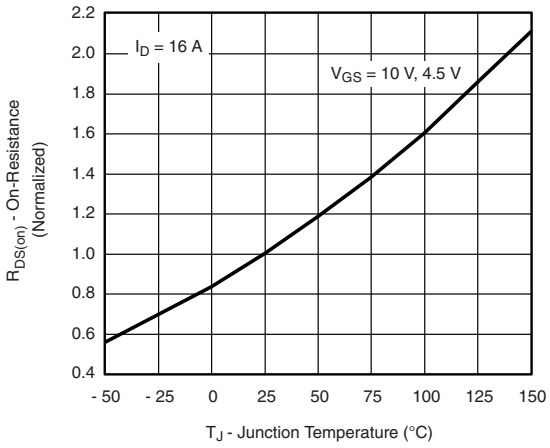

**On-Resistance vs. Drain Current and Gate Voltage**




**Capacitance**

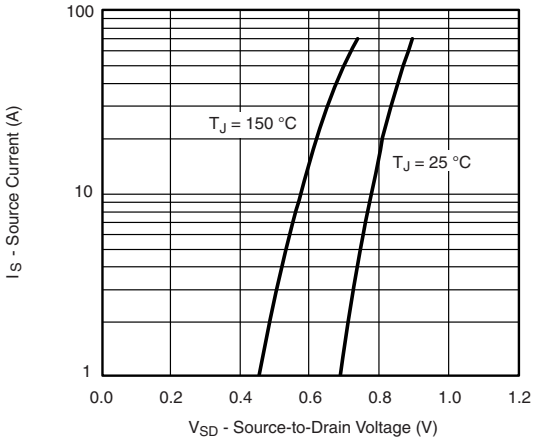



**Gate Charge**

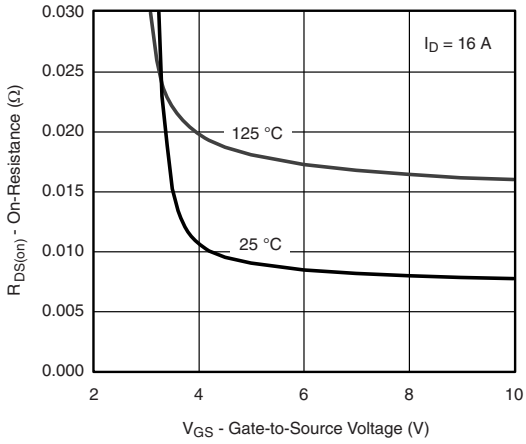



**On-Resistance vs. Junction Temperature**

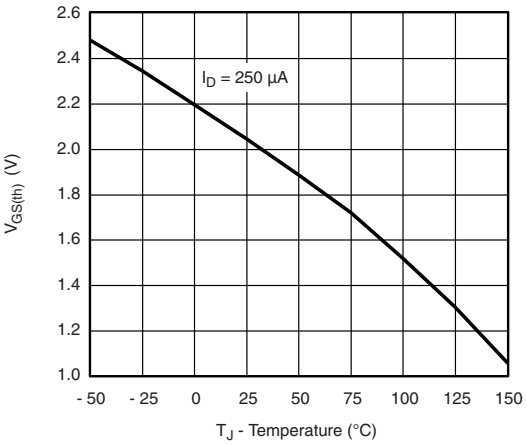
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



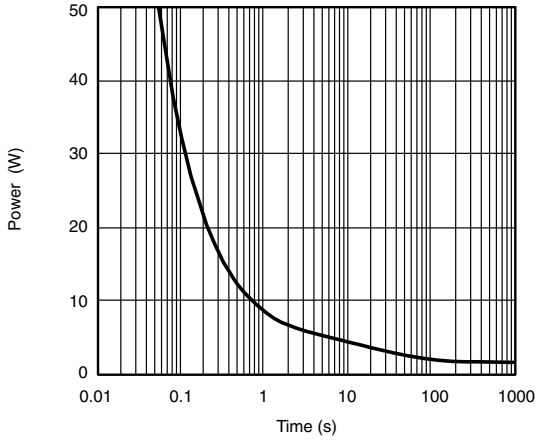

**Source-Drain Diode Forward Voltage**



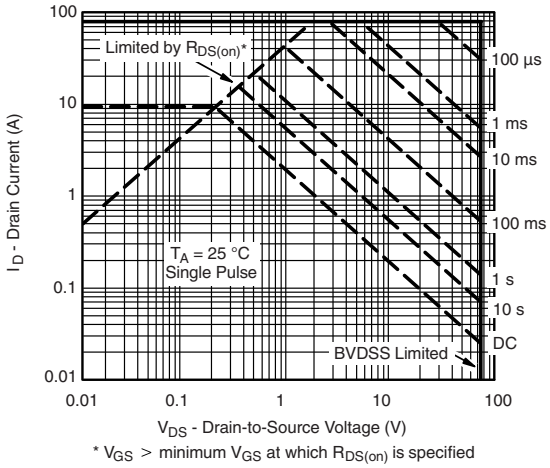

**On-Resistance vs. Gate-to-Source Voltage**




**Threshold Voltage**



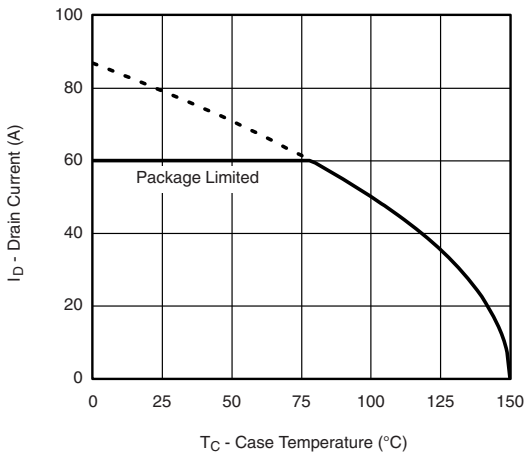

**Single Pulse Power, Junction-to-Ambient**



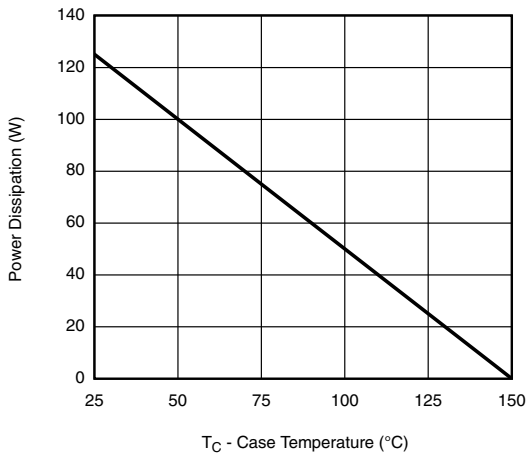

* $V_{GS}$ > minimum $V_{GS}$ at which $R_{DS(on)}$ is specified

**Safe Operating Area, Junction-to-Ambient**

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)




**Current Derating** [a]

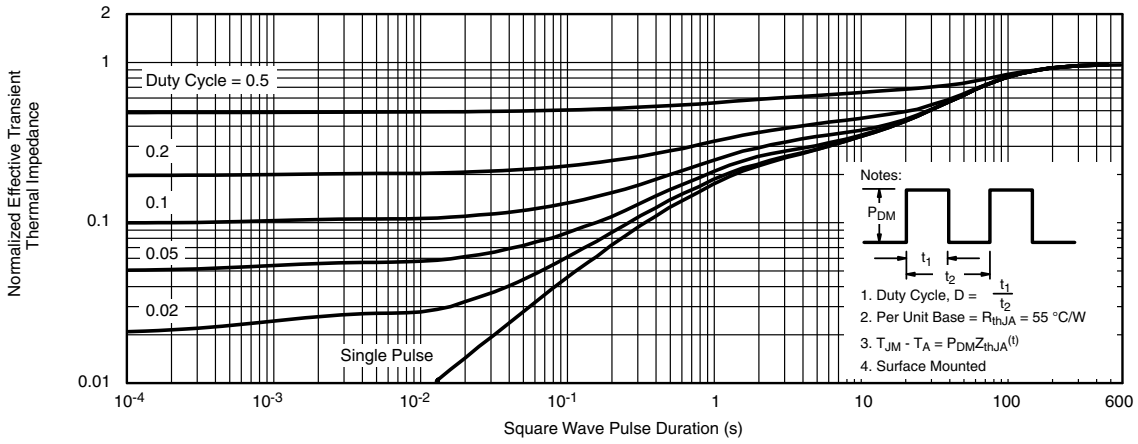



**Power Derating, Junction-to-Case**

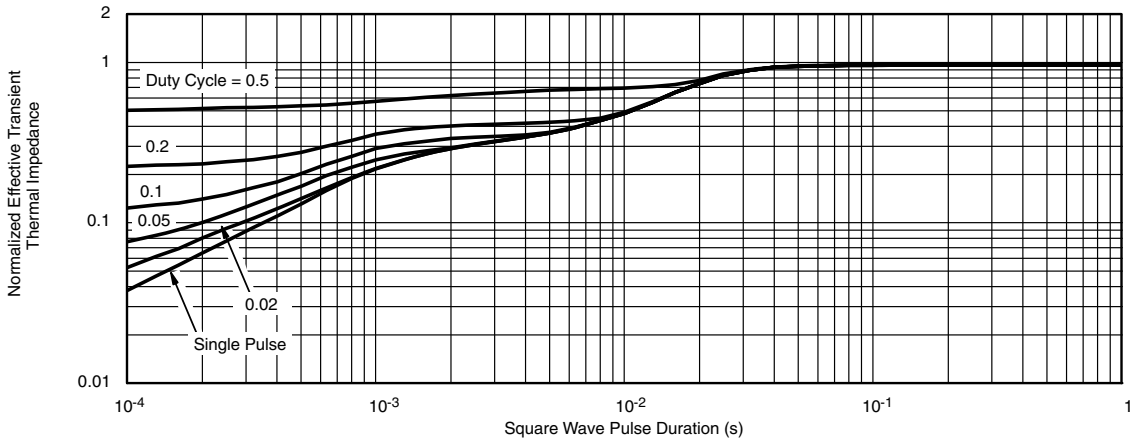
**Note**

a. The power dissipation $P_D$ is based on $T_J$ max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

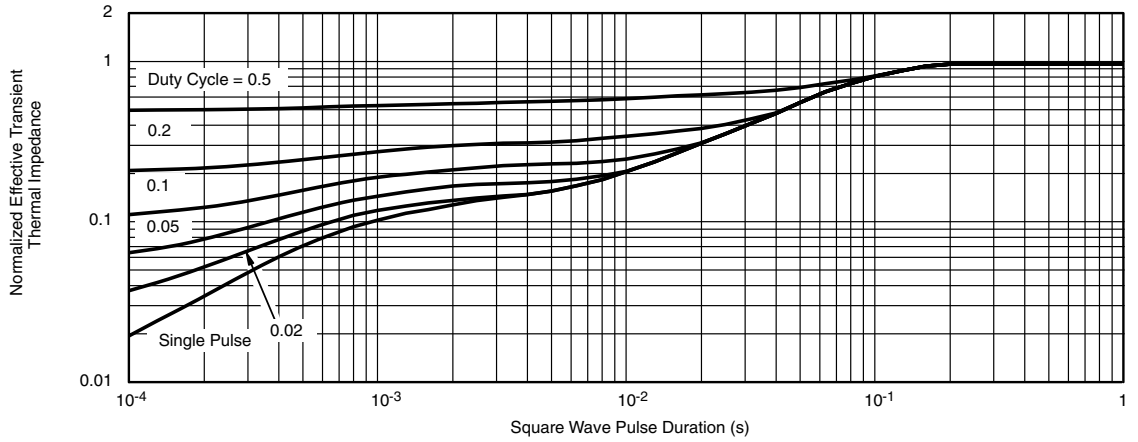
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)




**Normalized Thermal Transient Impedance, Junction-to-Ambient**




**Normalized Thermal Transient Impedance, Junction-to-Case (Drain Top)**

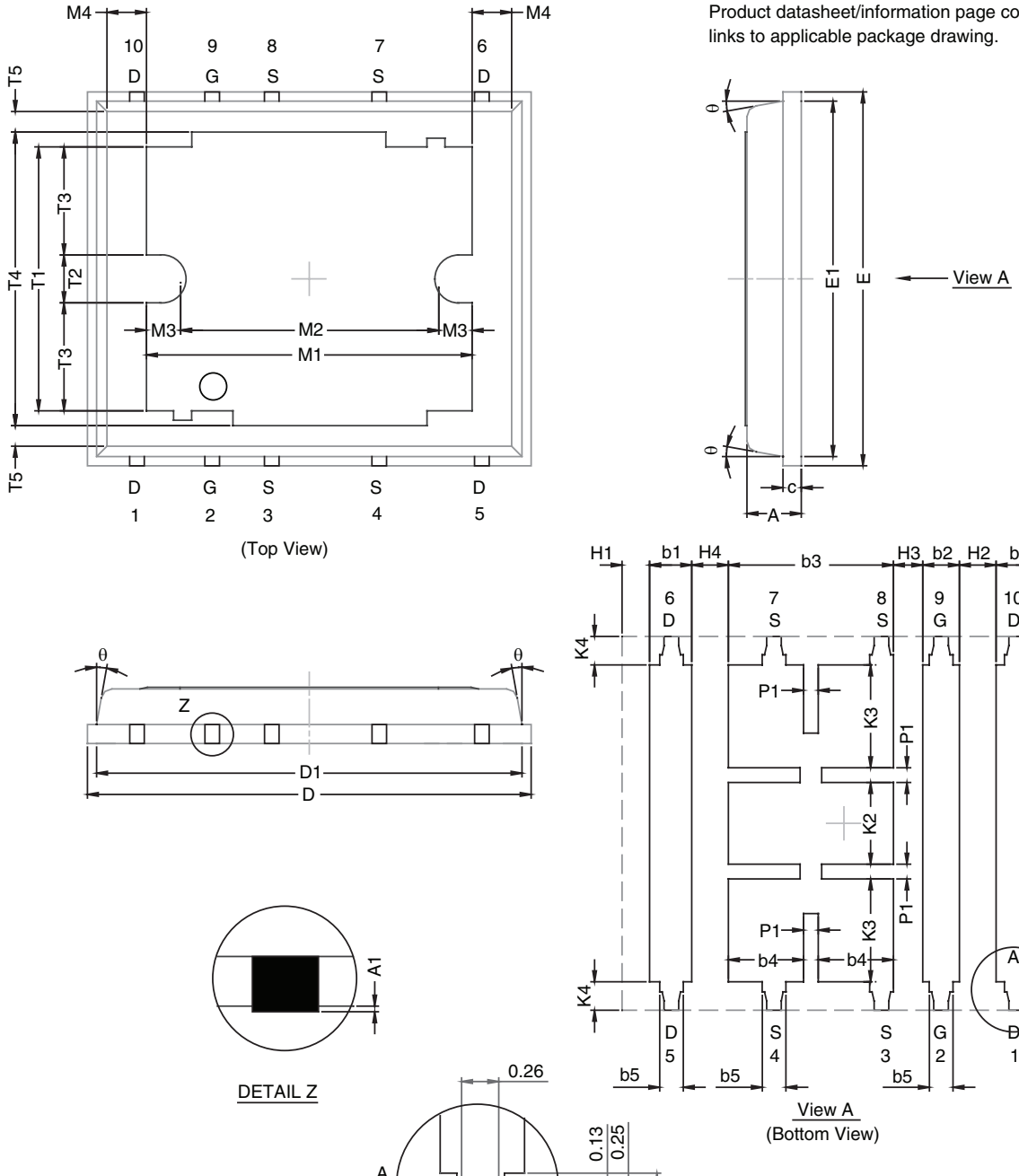



**Normalized Thermal Transient Impedance, Junction-to-Source**

*Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?74485.*

## POLARPAK™ OPTION L

Product datasheet/information page contain links to applicable package drawing.

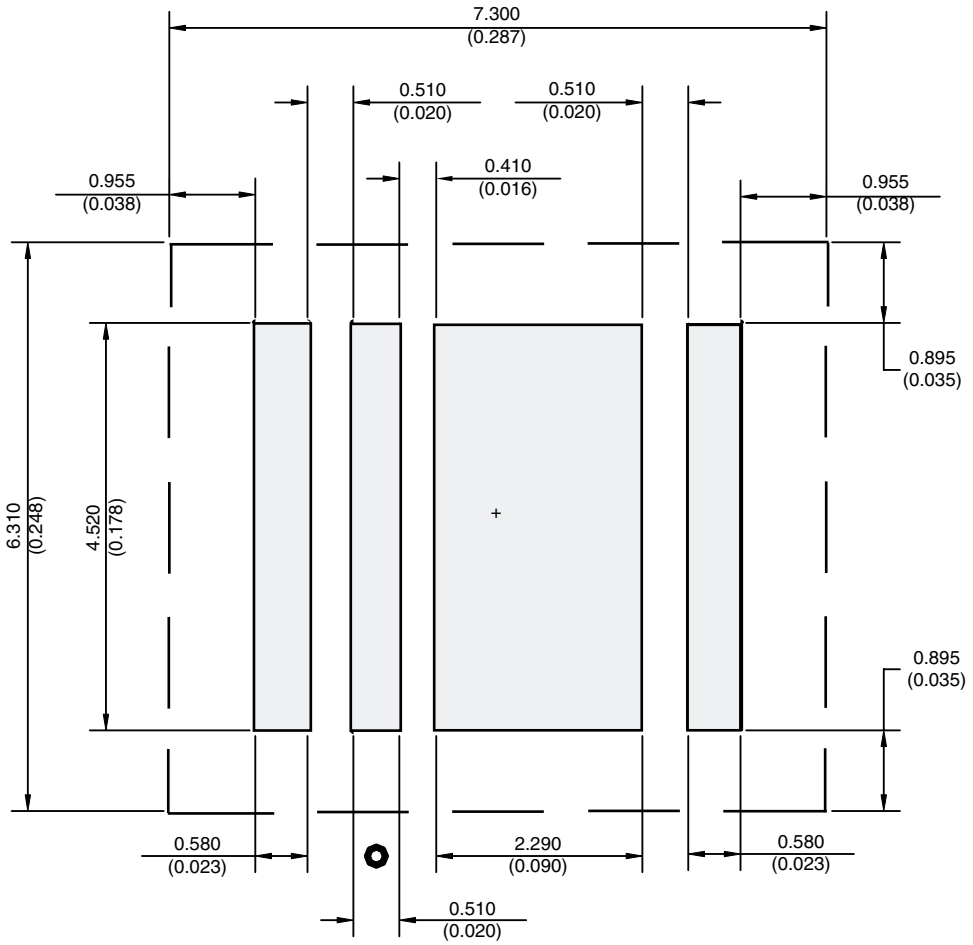


| DIM | MILLIMETERS | | | INCHES | | |
|---|---|---|---|---|---|---|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.75 | 0.80 | 0.85 | 0.030 | 0.031 | 0.033 |
| A1 | 0.00 | - | 0.05 | 0.000 | - | 0.002 |
| b1 | 0.48 | 0.58 | 0.68 | 0.019 | 0.023 | 0.027 |
| b2 | 0.41 | 0.51 | 0.61 | 0.016 | 0.020 | 0.024 |
| b3 | 2.19 | 2.29 | 2.39 | 0.086 | 0.090 | 0.094 |
| b4 | 0.89 | 1.04 | 1.19 | 0.035 | 0.041 | 0.047 |
| b5 | 0.23 | 0.33 | 0.43 | 0.009 | 0.013 | 0.017 |
| c | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 |
| D | 6.00 | 6.15 | 6.30 | 0.236 | 0.242 | 0.248 |
| D1 | 5.74 | 5.89 | 6.04 | 0.226 | 0.232 | 0.238 |
| E | 5.01 | 5.16 | 5.31 | 0.197 | 0.203 | 0.209 |
| E1 | 4.75 | 4.90 | 5.05 | 0.187 | 0.193 | 0.199 |
| H1 | 0.23 | - | - | 0.009 | - | - |
| H2 | 0.45 | - | 0.56 | 0.018 | - | 0.022 |
| H3 | 0.31 | 0.41 | 0.51 | 0.012 | 0.016 | 0.020 |
| H4 | 0.45 | - | 0.56 | 0.018 | - | 0.022 |
| K1 | 4.22 | 4.37 | 4.52 | 0.166 | 0.172 | 0.178 |
| K2 | 1.08 | 1.13 | 1.18 | 0.043 | 0.044 | 0.046 |
| K3 | 1.37 | - | - | 0.054 | - | - |
| K4 | 0.24 | - | - | 0.009 | - | - |
| M1 | 4.30 | 4.50 | 4.70 | 0.169 | 0.177 | 0.185 |
| M2 | 3.43 | 3.58 | 3.73 | 0.135 | 0.141 | 0.147 |
| M3 | 0.22 | - | - | 0.009 | - | - |
| M4 | 0.05 | - | - | 0.002 | - | - |
| P1 | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| T1 | 3.48 | 3.64 | 4.10 | 0.137 | 0.143 | 0.161 |
| T2 | 0.56 | 0.76 | 0.95 | 0.022 | 0.030 | 0.037 |
| T3 | 1.20 | - | - | 0.047 | - | - |
| T4 | 3.90 | - | - | 0.153 | - | - |
| T5 | 0 | 0.18 | 0.36 | 0.000 | 0.007 | 0.014 |
| θ | 0° | 10° | 12° | 0° | 10° | 12° |
| ECN: T-08441-Rev. C, 11-Aug-08<br>DWG: 5946 | | | | | | |

**Notes**

Millimeters govern over inches.

## RECOMMENDED MINIMUM PADS FOR PolarPAK® Option L and S




Recommended Minimum for PolarPAK Option L and S
Dimensions in mm/(Inches)
No External Traces within Broken Lines
Dot indicates Gate Pin (Part Marking)

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